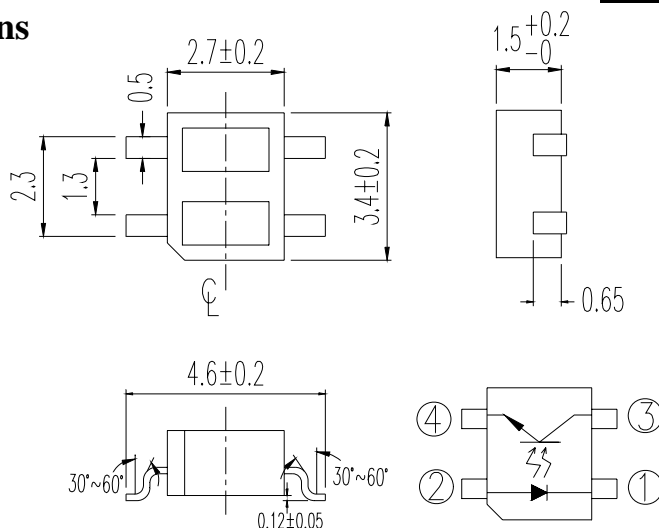


Package Dimensions



①: CATHODE

③: COLLECTOR

②: ANODE

④: EMITTER

Notes: 1.All dimensions are in millimeters

2.Tolerances unless dimensions $\pm 0.15\text{mm}$

Absolute Maximum Ratings ($T_a=25^\circ\text{C}$)

Parameter		Symbol	Ratings	Unit
Input	Power Dissipation at(or below) 25°C Free Air Temperature	P_d	75	mW
	Reverse Voltage	V_R	5	V
	Forward Current	I_F	50	mA
	Peak Forward Current (*1) Pulse width $\leq 100 \mu\text{s}$, Duty cycle=1%	I_{FP}	1	A
Output	Collector Power Dissipation	P_C	75	mW
	Collector Current	I_C	50	mA
	Collector-Emitter Voltage	$B V_{CEO}$	30	V
	Emitter-Collector Voltage	$B V_{ECO}$	5	V
Operating Temperature		T_{opr}	$-25 \sim +85$	$^\circ\text{C}$
Storage Temperature		T_{stg}	$-30 \sim +90$	$^\circ\text{C}$
Lead Soldering Temperature (*2)		T_{sol}	260	$^\circ\text{C}$

(* 1) $t_w=100 \mu\text{sec.}$, $T=10 \text{ msec.}$

(* 2) $t=5 \text{ Sec}$

Electro-Optical Characteristics (Ta=25°C)

Parameter		Symbol	Min.	Typ.	Max.	Unit	Conditions
Input	Forward Voltage	V_F	---	1.2	1.6	V	$I_F=20\text{mA}$
	Reverse Current	I_R	---	---	10	μA	$V_R=5\text{V}$
	Peak Wavelength	λ_P	---	940	---	nm	---
Output	Dark Current	I_{CEO}	---	---	100	nA	$V_{CE}=10\text{V}$
	C-E Saturation Voltage	$V_{CE(sat)}$	---	---	0.4	V	$I_C=2\text{mA}$ $E_e=1\text{mW/cm}^2$
Transfer Characteristics	Light Current	$I_C(ON)$	0.3	---	0.8	mA	$V_{CE}=5\text{V}$
	Leakage Current	I_{CEOD}	---	---	1	μA	$I_F=20\text{mA}$
	Rise time	t_r	---	20	---	μsec	$V_{CE}=2\text{V}$
	Fall time	t_f	---	20	---	μsec	$I_C=100\mu\text{A}$ $R_L=1\text{K}\Omega$

Rank

Conditions : $I_F=20\text{mA}$ $V_{CE}=5\text{V}$

Unit: μA

Bin number	Min	Max
B	300	600
C	500	800

Typical Electrical/Optical/Characteristics Curves for IR

Fig. 1 Forward Current vs. Ambient Temperature

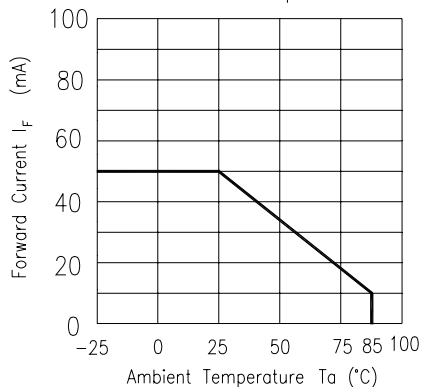


Fig. 2 Spectral Distribution

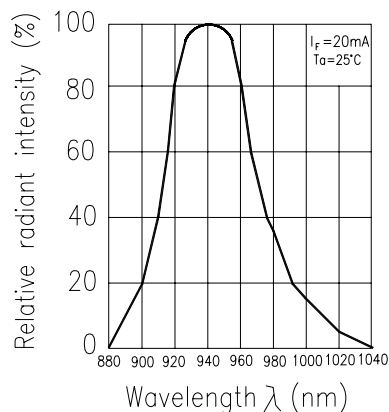


Fig. 3 Peak Emission Wavelength vs. Ambient Temperature

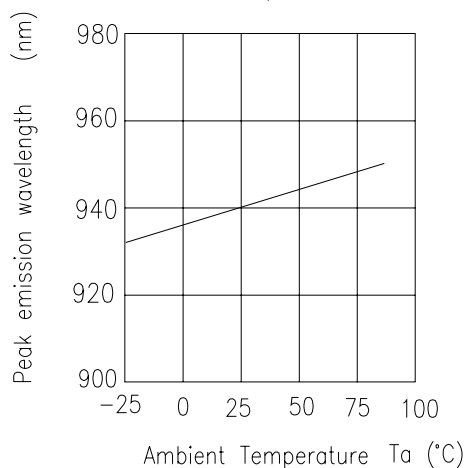


Fig. 4 Forward Current vs. Forward Voltage

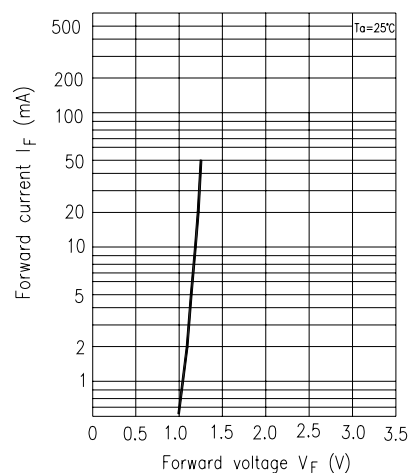


Fig. 5 Forward Voltage vs. Ambient Temperature

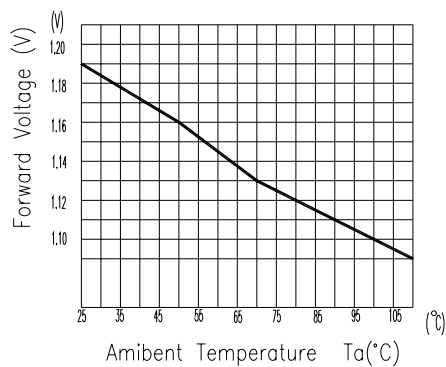
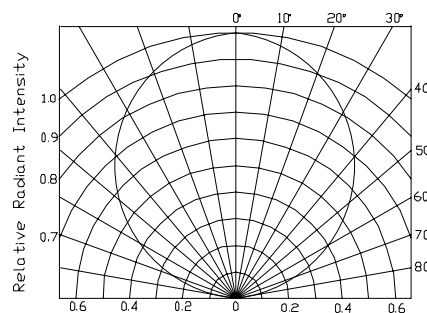


Fig. 6 Relative Radiant Intensity vs. Angular Displacement



Typical Electro/Optical/Characteristics Curves for PT

Fig.1 Collector Power Dissipation vs. Ambient Temperature

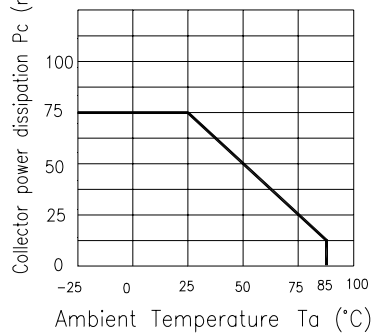


Fig.2 Collector Dark Current vs. Ambient Temperature

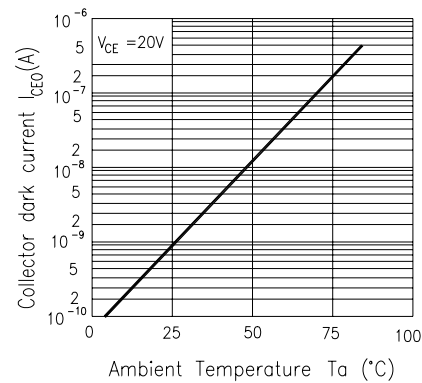


Fig. 3 Relative Collector Current vs. Ambient Temperature

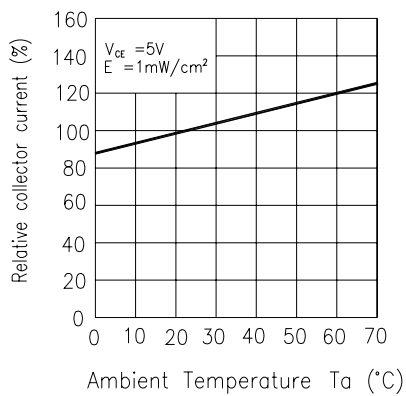


Fig.4 Collector Current vs. Irradiance

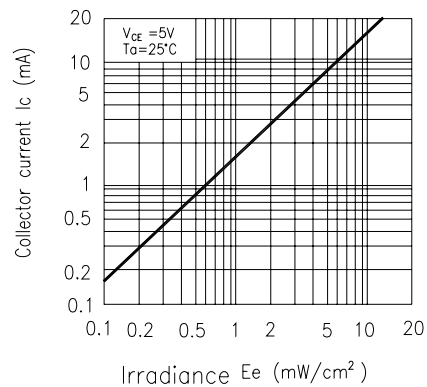


Fig.5 Spectral Sensitivity

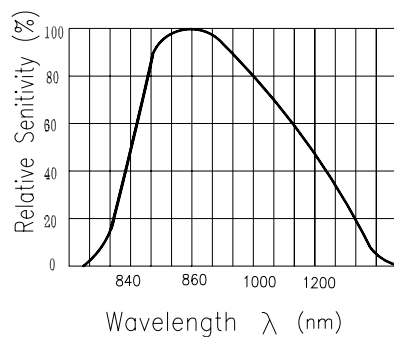
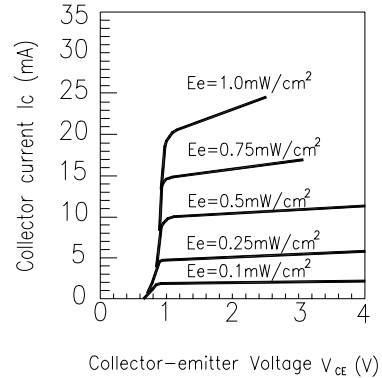


Fig.6 Collector Current vs. Collector-emitter Voltage



Typical Electrical/Optical/Characteristics Curves For ITR

Fig.1 Relative Collector Current vs. Distance between Sensor and Al Evaporation Galss

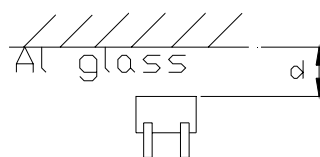
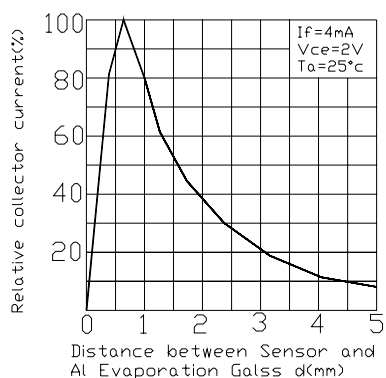


Fig.2 Relative Collector Current vs. Card Moving Distance (1)

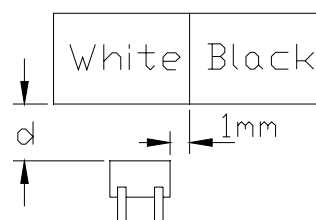
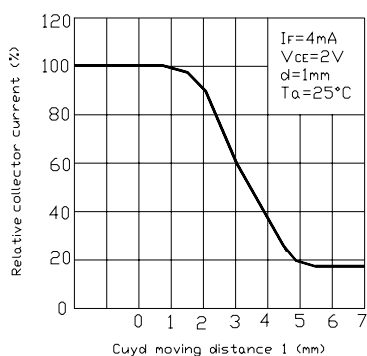
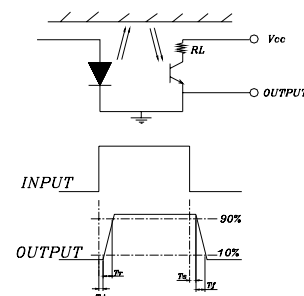
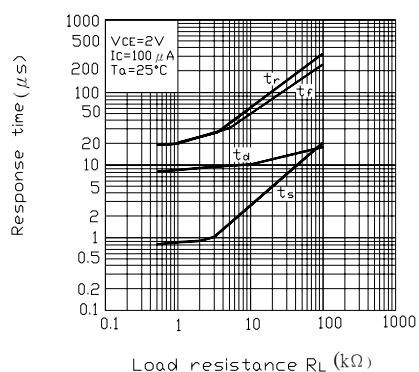


Fig.3 Response Time vs. Load Resistance



Reliability Test Item And Condition

The reliability of products shall be satisfied with items listed below.

Confidence level : 90%

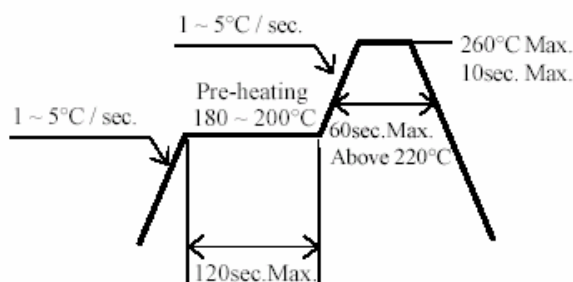
LTPD : 10%

NO.	Item	Test Conditions	Test Hours/ Cycles	Sample Sizes	Failure Judgement Criteria	Ac/Re
1	Solder Heat	TEMP. : $260^{\circ}\text{C} \pm 5^{\circ}\text{C}$	10secs	22pcs	$I_R \geq U \times 2$ $E_e \leq L \times 0.8$ $V_F \geq U \times 1.2$ U : Upper Specification Limit L : Lower Specification Limit	0/1
2	Temperature Cycle	H : $+85^{\circ}\text{C}$ 30mins \updownarrow 5mins L : -55°C 30mins	50Cycles	22pcs		0/1
3	Thermal Shock	H : $+100^{\circ}\text{C}$ 5mins \updownarrow 10secs L : -10°C 5mins	50Cycles	22pcs		0/1
4	High Temperature Storage	TEMP. : $+100^{\circ}\text{C}$	1000hrs	22pcs		0/1
5	Low Temperature Storage	TEMP. : -55°C	1000hrs	22pcs		0/1
6	DC Operating Life	$I_F = 20\text{mA}$	1000hrs	22pcs		0/1
7	High Temperature/ High Humidity	85°C / 85% R.H	1000hrs	22pcs		0/1

Recommended Method of Storage

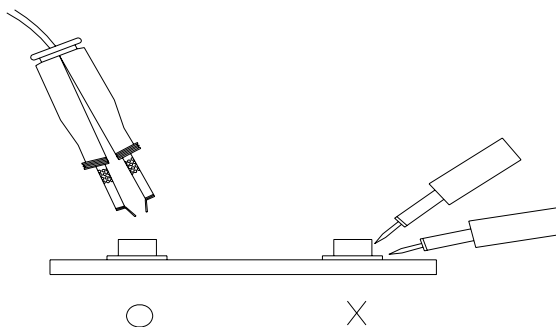
The following are general recommendations for moisture sensitive level (MSL) 4 storage and use:

- Shelf life in sealed bag: 12 months at $< 40^{\circ}\text{C}$ and $< 90\%$ relative humidity (RH)
- After bag is opened, devices that will be subjected to reflow solder or other high temperature process must
 - a) Mounted within 72 hours of factory conditions $< 30^{\circ}\text{C}/60\%\text{RH}$, or
 - b) Stored at $< 20\%$ RH
- Devices require bake, before mounting, if:
Humidity Indicator Card is $> 20\%$ when read at $23 \pm 5^{\circ}\text{C}$
- If baking is required, devices may be baked:
 - a) 192 hours at 40°C , and $< 5\%$ RH (dry air/nitrogen) or
 - b) 96 hours at 60°C , and $< 5\%$ RH for all device containers
 - c) 24 hours at 125°C
- Soldering Condition
 - a) Pb-free solder temperature profile



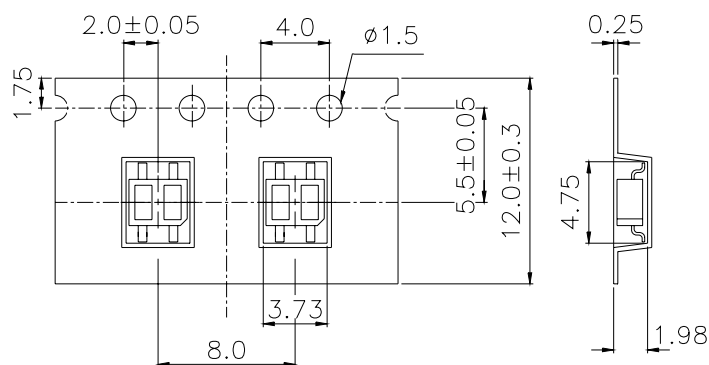
- b) Reflow soldering should not be done more than two times.
 - c) When soldering, do not put stress on the LEDs during heating.
 - d) After soldering, do not warp the circuit board.
- Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



Taping Dimension

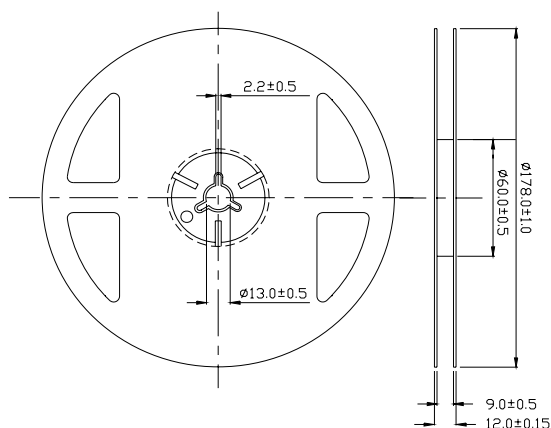
Progressive direction →



General Tolerance ± 0.1

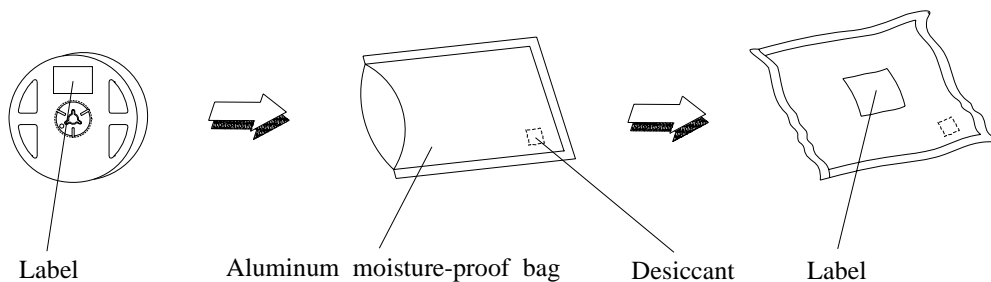
UNIT:mm

Reel Dimensions



Note: The tolerances unless mentioned is $\pm 0.1\text{mm}$,Unit = mm

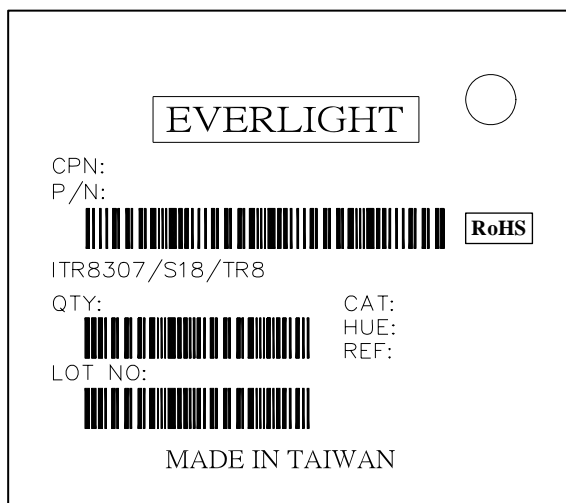
Moisture Resistant Packaging



Packing Quantity Specification

1. 1000 Pcs/ 1Reel
2. 15 Reel /1 Box
3. 2 Box/ 1 Carton

Label Form Specification



The diagram shows a rectangular label form with the following elements:

- EVERLIGHT logo in a box at the top center.
- A circle at the top right.
- CPN: and P/N: labels on the left.
- A large barcode in the center.
- A RoHS logo in a box on the right.
- ITR8307/S18/TR8 text below the main barcode.
- QTY: label on the left, followed by a smaller barcode.
- CAT: label on the right.
- HUE: label on the right.
- REF: label on the right.
- LOT NO: label on the left, followed by a smaller barcode.
- MADE IN TAIWAN text at the bottom center.

CPN: Customer's Production Number

P/N : Production Number

QTY: Packing Quantity

CAT: None

HUE: None

REF: Reference

LOT No: Lot Number

MADE IN TAIWAN: Production Place

Notes

1. Above specification may be changed without notice. EVERLIGHT will reserve authority on material change for above specification.
2. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
3. These specification sheets include materials protected under copyright of EVERLIGHT corporation. Please don't reproduce or cause anyone to reproduce them without EVERLIGHT's consent.

EVERLIGHT ELECTRONICS CO., LTD.

Office: No 25, Lane 76, Sec 3, Chung Yang Rd,
Tucheng, Taipei 236, Taiwan, R.O.C

Tel: 886-2-2267-2000, 2267-9936

Fax: 886-2267-6244, 2267-6189, 2267-6306

<http://www.everlight.com>